

Title (en)
Abrasive tool

Title (de)
Schleifwerkzeug

Title (fr)
Outil abrasif

Publication
EP 1122030 A3 20031210 (EN)

Application
EP 01101689 A 20010130

Priority
JP 2000029614 A 20000207

Abstract (en)
[origin: EP1500469A1] An abrasive tool (420) with metal binder phase has plural protruded parts formed in base metal (422), and has abrasive grain layer (424) with small abrasive-grain-layer parts (428) set at an interval mutually and ultra abrasive grains (14,414) are adhered at these protruded parts by metal binder phase. A single ultra abrasive grain is adhered at each of said small abrasive-grain-layer parts by the metal binder phase.
<IMAGE>

IPC 1-7
B24D 3/06; **B24D 7/00**; **B24B 37/04**; **B24B 53/12**; **B24D 18/00**

IPC 8 full level
B24B 53/12 (2006.01); **B24D 3/00** (2006.01); **B24D 3/06** (2006.01); **B24D 7/06** (2006.01); **B24D 18/00** (2006.01)

CPC (source: EP KR)
B24B 53/017 (2013.01 - EP); **B24B 53/12** (2013.01 - EP); **B24D 3/06** (2013.01 - EP KR); **B24D 7/06** (2013.01 - EP); **B24D 18/0018** (2013.01 - EP)

Citation (search report)
• [X] US 5989405 A 19991123 - MURATA YASUNORI [JP], et al
• [X] US 6001008 A 19991214 - FUJIMORI KEIICHI [JP], et al
• [X] US 6004196 A 19991221 - DOAN TRUNG T [US], et al
• [X] PATENT ABSTRACTS OF JAPAN vol. 1999, no. 08 30 June 1999 (1999-06-30)
• [X] PATENT ABSTRACTS OF JAPAN vol. 018, no. 396 (M - 1644) 25 July 1994 (1994-07-25)
• [DA] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 05 30 May 1997 (1997-05-30)

Cited by
CN103551999A; EP1595645A4; CN107912026A; US6669745B2; WO2017007703A1; WO2068154A1; WO2006132725A1; US7357705B2; US10919126B2

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
EP 1122030 A2 20010808; **EP 1122030 A3 20031210**; **EP 1122030 B1 20060628**; AT E331591 T1 20060715; DE 60121070 D1 20060810; DE 60121070 T2 20070606; EP 1500469 A1 20050126; HK 1039296 A1 20020419; JP 2001219376 A 20010814; KR 100749385 B1 20070814; KR 20010078363 A 20010820

DOCDB simple family (application)
EP 01101689 A 20010130; AT 01101689 T 20010130; DE 60121070 T 20010130; EP 04024424 A 20010130; HK 02100678 A 20020129; JP 2000029614 A 20000207; KR 20010005927 A 20010207